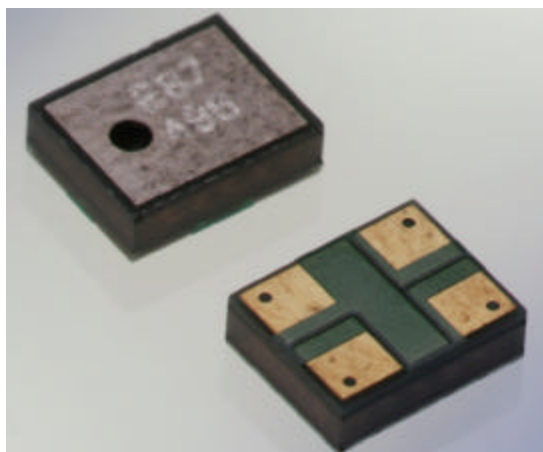


## “Mini” SiSonic™ Microphone Specification



**Knowles Acoustics**  
1151 Maplewood Drive  
Itasca, IL 60143

## 1. DESCRIPTION AND APPLICATION

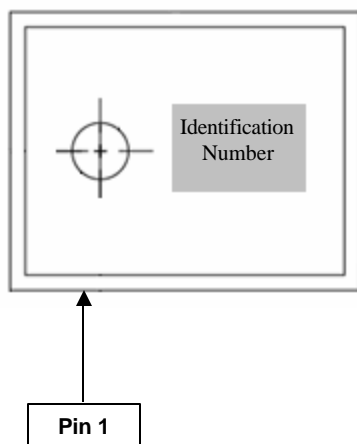
### 1.1 Description

“Mini” Surface Mount Silicon Microphone  
with Enhanced RF Protection

### 1.2 Application

Hand held telecommunication devices

## 2. PART MARKING



### Identification Number Convention

|   |   |   |   |
|---|---|---|---|
| S | 1 | 2 | 3 |
| 4 | 5 | 6 |   |

S: Manufacturing Location

“S” – Knowles Electronics Suzhou  
Suzhou, China

“No Alpha Character” – Knowles Electronics Itasca  
Itasca, IL USA

“E” – Engineering Samples

Digits 1 – 6: Job Identification Number

## 3. TEMPERATURE RANGE

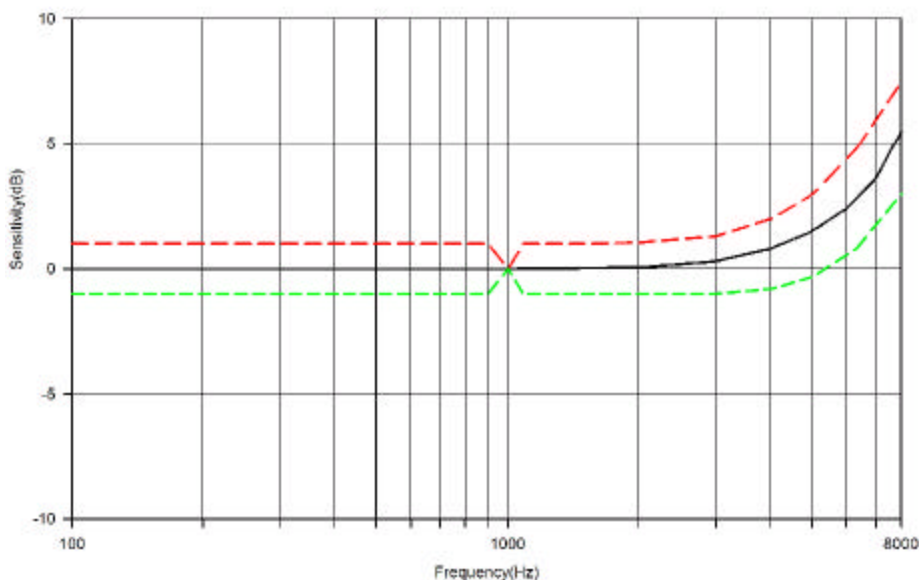
3.1 Operating Temperature Range: -40°C to +100°C

3.2 Storage Temperature Range: -40°C to +100°C

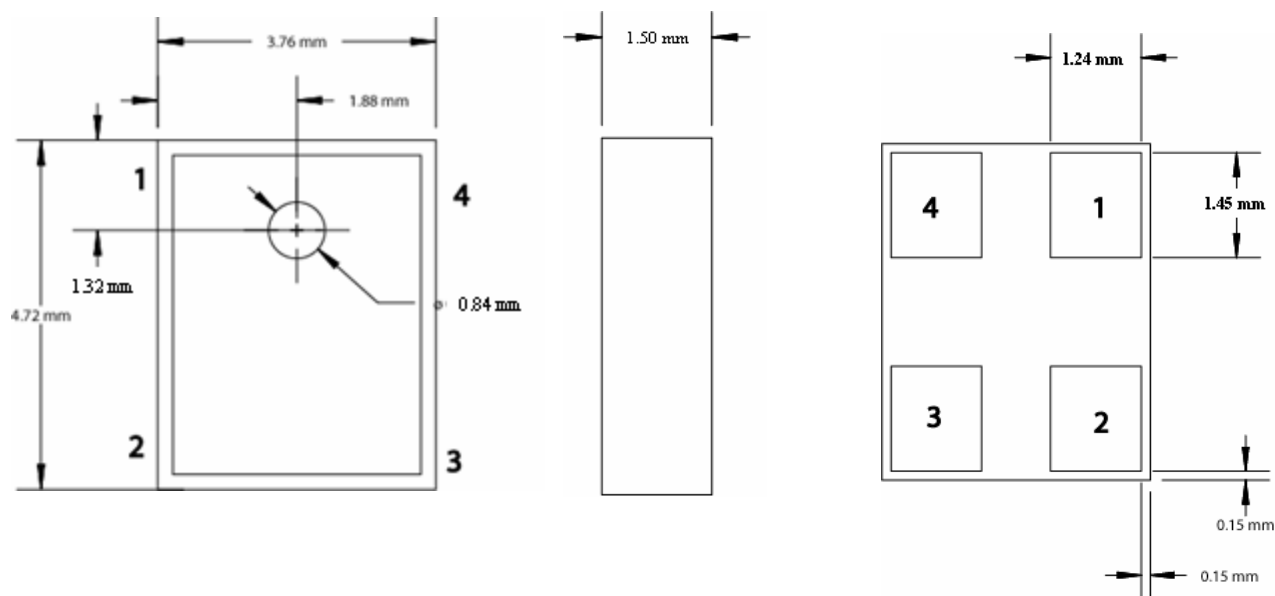
## 4. ACOUSTIC & ELECTRICAL SPECIFICATIONS

|                                 | Symbol           | Condition   | Limits                         |      |       | Unit    |
|---------------------------------|------------------|---|--------------------------------|------|-------|---------|
|                                 |                  |   | Min.                           | Nom. | Max.  |         |
| Directivity                     |                  | Omni-directional                                    |                                |      |       |         |
| Sensitivity                     | S                | @ 1kHz (0dB=1V/Pa)                                  | -46                            | -42  | -38   | dB      |
| Output impedance                | Z <sub>OUT</sub> | @ 1kHz (0dB=1V/Pa)                                  | n/a                            | n/a  | 100   | Ω       |
| Current Consumption             | I <sub>DSS</sub> | across 1.5 to 5.5 volts                             | 0.100                          | n/a  | 0.250 | mA      |
| Signal to Noise Ratio           | S/N              | @ 1kHz (0dB=1V/Pa)                                  | 55                             | 59   | n/a   | dB      |
| Supply Voltage                  | Vs               |   | 1.5                            | n/a  | 5.5   | V       |
| Typical Input Referred Noise    | ENL              | A-weighted  | n/a                            | 35   | n/a   | dBA SPL |
| Sensitivity Loss across Voltage |                  | Change in sensitivity over 5.5v to 1.5v             | No Change Across Voltage Range |      |       | dB      |
| Maximum Input Sound Level       |                  | At 100dB SPL, THD < 1%<br>At 115dB SPL, THD = < 10% |                                |      |       | dB      |

## 5. FREQUENCY RESPONSE CURVE



## 6. MECHANICAL SPECIFICATIONS

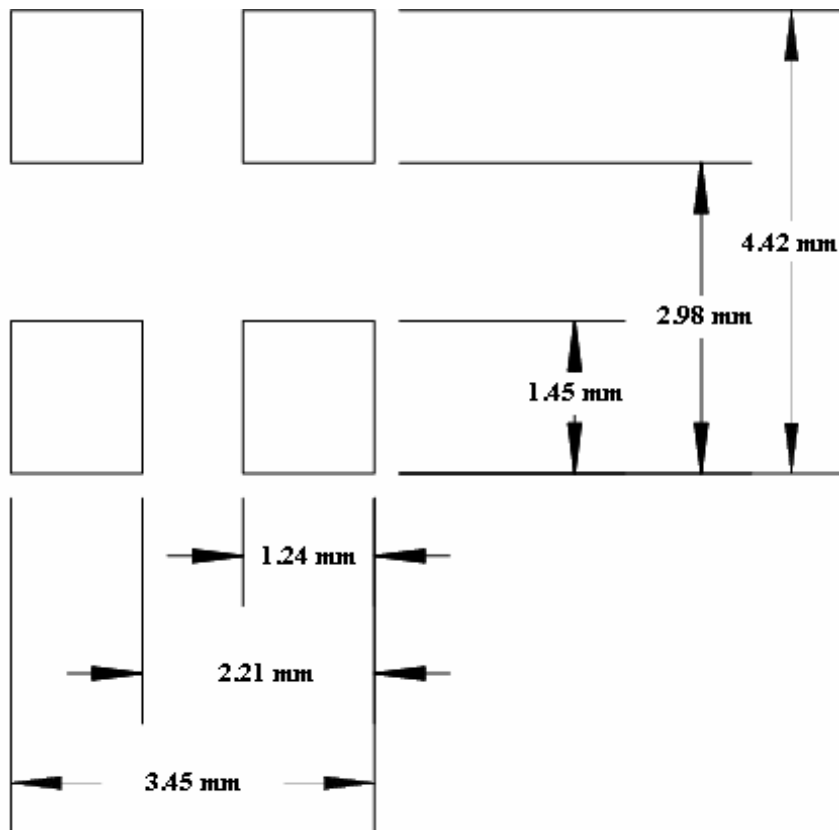


| Pin Output |          |
|------------|----------|
| Pin #      | Function |
| 1          | Output   |
| 2          | Ground   |
| 3          | Ground   |
| 4          | Power    |

| Item                         | Dim. | Tol. (+/-)     | Units |
|------------------------------|------|----------------|-------|
| Height                       | 1.50 | +0.20<br>-0.10 | mm    |
| Length                       | 4.72 | 0.10           | mm    |
| Width                        | 3.76 | 0.10           | mm    |
| Port Hole                    | 0.84 | 0.15           | mm    |
| Short Edge to C.L. Port      | 1.32 | 0.25           | mm    |
| Long Edge to C.L. Port       | 1.88 | 0.25           | mm    |
| Weight                       | 0.08 | grams          |       |
| Coplanarity                  | <0.1 | mm             |       |
| Acoustic Seal I.D. (typical) | 1.55 | mm             |       |

Note: (Tolerance +/-0.15mm unless otherwise specified)

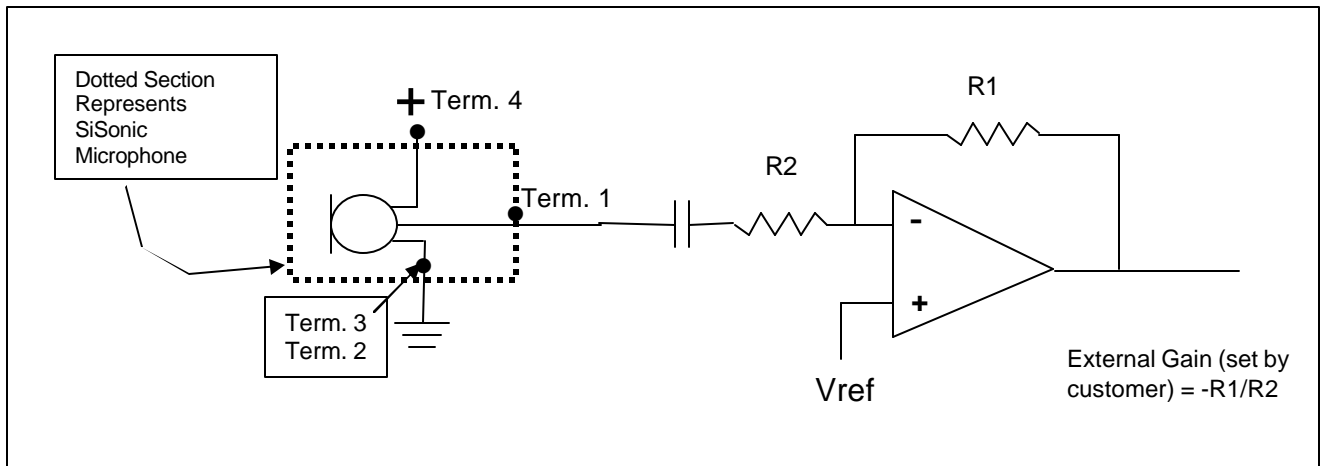
## 7. RECOMMENDED CUSTOMER LAND PATTERN



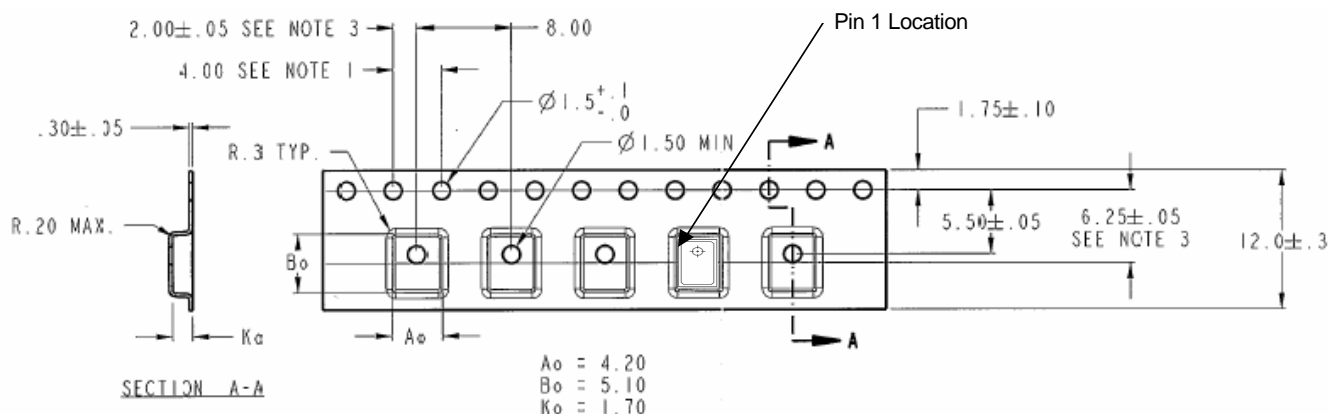
## 8. RECOMMENDED SOLDER STENCIL PATTERN

N/A

## 9. RECOMMENDED INTERFACE CIRCUIT



## 10. PACKAGING DETAIL



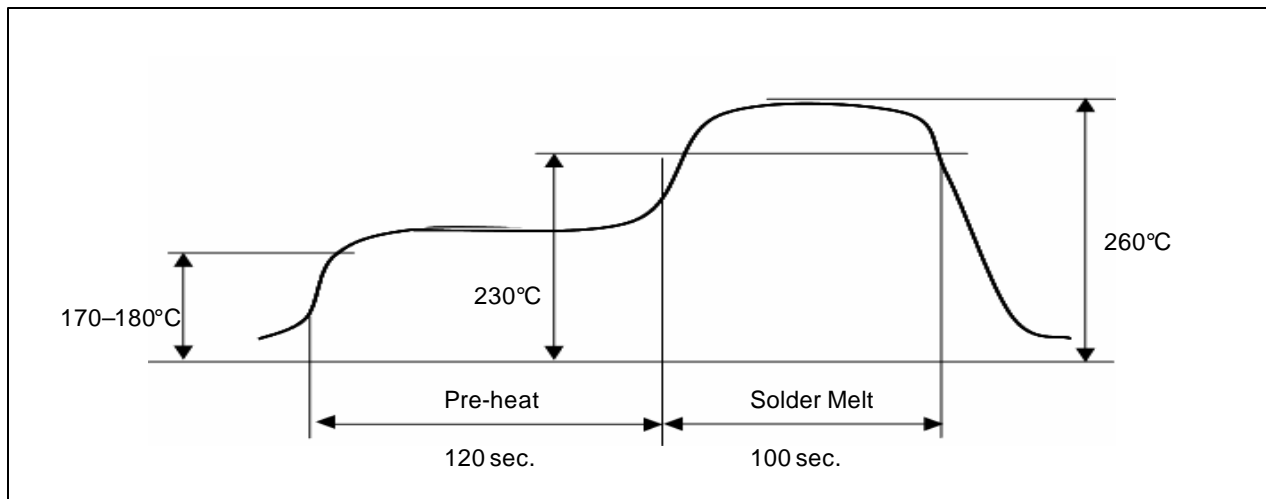
### NOTES:

1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE  $\pm 0.2$
2. CAMBER IN COMPLIANCE WITH EIA 481
3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

| Model Number | Suffix | Reel Diameter | Quantity per Reel | RF Protection |
|--------------|--------|---------------|-------------------|---------------|
| SPM0102NE3   | -2     | 7"            | 1200              | Enhanced      |
| SPM0102NE3   | -3     | 13"           | 4500              | Enhanced      |

|               |   |
|---------------|---|
| Tape & Reel   | Available in 13" and 7" diameter.   |
| Leader Length | 800mm or minimum of 100 empty pockets   |
| Label         | Label applied to external package and direct to reel. Per JEDEC.  |
| Empty Units   | No consecutive empty pockets; No more than 3 empty pockets per reel. (Does not include empty pockets for leader/follower) |

## 11. SOLDER REFLOW PROFILE



| <i><u>Stage</u></i> | <i><u>Temperature Profile</u></i> | <i><u>Time (maximum)</u></i> |
|---------------------|-----------------------------------|------------------------------|
| Pre-heat            | 170 ~ 180 C                       | 120 sec.                     |
| Solder Melt         | Above 230 C                       | 100 sec.                     |
| Peak                | 260 C maximum                     | 30 sec.                      |

### Notes:

1. Do not pull a vacuum over the port hole of the microphone. Pulling a vacuum over the port hole can damage the device.
2. Do not board wash after the reflow process. Board washing and cleaning agents can damage the device. Do not expose to ultrasonic processing or cleaning.
3. Number of Reflow = recommend no more than 3 cycles.

## 12. ADDITIONAL NOTES

- (A) Packaging (reference SiSonic\_Packaging\_Spec.pdf)
- (B) Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.
- (C) Exposure: Devices should not be exposed to high humidity, high temperature environment. MSL (moisture sensitivity level) Class 2A.
- (D) Out of bag: Maximum of 90 days out of ESD moisture sensitive bag, assuming maximum conditions of 30°C/70% R.H.



## 13. RELIABILITY SPECIFICATIONS

Note: After test conditions are performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

| Test                            | Description   |
|---------------------------------|---|
| Thermal Shock                   | Microphone unit must operate when exposed to air-to-air thermal shock 100 cycles, from $-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$ . (IEC 68-2-4),  |
| High Temperature Storage Test   | Microphone unit must maintain sensitivity after storage at $+105^{\circ}\text{C}$ for 1,000 hours. (IEC 68-2-2 Test Ba)   |
| Low Temperature Storage Test    | Microphone unit must maintain sensitivity after storage at $-40^{\circ}\text{C}$ for 1,000 hours. (IEC 68-2-1 Test Aa)  |
| High Temperature Operating Test | Microphone unit must operate within sensitivity specifications for 1,000 hours at $105^{\circ}\text{C}$ . (IEC 68-2-2 Test Ba)  |
| Low Temperature Operating Test  | Microphone unit must operate within sensitivity specifications for 1,000 hours at $-40^{\circ}\text{C}$ . (IEC 68-2-1 Test Aa)  |
| Humidity Test                   | Tested under Bias at $85^{\circ}\text{C}/85\%$ R.H. for 1,000 hours. (JESD22-A101A-B)   |
| Vibration Test                  | Microphone unit must operate under test condition: 4 cycles, from 20 to 2,000 Hz in each direction (x,y,z), 48 minutes, using peak acceleration of 20 G (+20%, -0%). (MIL 883E, method 2007.2, A) |
| Electrostatic Discharge         | Tested to 8kV direct contact discharge or 15kV air discharge as specified by IEC 1000-4-2, level 3 and level 4.   |
| Reflow                          | Microphone is tested to 5 passes through reflow oven, with microphone mounted upside-down under conditions of $260^{\circ}\text{C}$ for 30 seconds maximum.                                       |
| Mechanical Shock                | Microphone must operate after exposure to shock test of 10,000 G per IEC 68-2-27, Ea.   |

## 14. SPECIFICATION REVISIONS

| Revision | Detailed Specification Changes   | Date       |
|----------|--|------------|
| A        | Preliminary Specification Release  | 01/06/2005 |
| B        | Section 5: Updated Response Curve  | 02/14/2005 |
| C        | Official Release. Section 6: Updated Mechanical Specifications.<br>Section 11: Updated Reflow Profile. Section 12: Updated<br>Additional Notes | 04/11/2005 |
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